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WHAT IS CLAIMED IS:

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1. A semiconductor device substrate, comprising:
a substrate body having a wiring layer;
a base formed by a material that is different
from a material of said substrate body, supporting said
10 substrate body, and having an opening forming portion
where a semiconductor element is mounted; and
a reinforcing member larger than the opening
forming portion, provided in said substrate body at a
portion corresponding to the opening forming portion, and
15 reinforcing said substrate body at the portion
corresponding to the opening forming portion.
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2. The semiconductor device substrate as claimed
in claim 1, wherein the reinforcing member is a circuit
board having a capacitor part that electrically connects
the semiconductor element and the wiring layer.
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3. The semiconductor device substrate as claimed
30 in claim 2, wherein the reinforcing member is arranged on
the base via an abutting member made of a metal.

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4. The semiconductor device substrate as claimed
in claim 1, wherein the reinforcing member is an
5 interposer having a via that directly electrically
connects the semiconductor element and the wiring layer.

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5. The semiconductor device substrate as claimed
in claim 4, wherein the reinforcing member is arranged on
the base via an abutting member made of a metal.

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6. The semiconductor device substrate as claimed
in claim 1, wherein the reinforcing member is arranged on
20 the base via an abutting member made of a metal.

25 7. A manufacturing method of a substrate, said
manufacturing method comprising the steps of:
manufacturing a reinforcing member;
arranging the reinforcing member on a base at a
portion corresponding to an opening forming portion of the
30 base;

forming a substrate body on the base on which
the reinforcing member is arranged, said substrate body
including a wiring layer and made of a material that is

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different from a material of the base; and

forming the opening forming portion smaller than the reinforcing member, thereby exposing a part of the reinforcing member at the opening forming portion.

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8. The manufacturing method as claimed in claim 7, wherein the step of manufacturing the reinforcing member includes a step of forming a capacitor on a core member.

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9. The manufacturing method as claimed in claim 8, wherein the step of manufacturing the reinforcing member includes a step of forming a via penetrating the core member.

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10. The manufacturing method as claimed in claim 9, wherein the reinforcing member is arranged on the base via an abutting member made of a metal.

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11. The manufacturing method as claimed in claim 8, wherein the reinforcing member is arranged on the base via an abutting member made of a metal.

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5 12. The manufacturing method as claimed in claim
7, wherein the reinforcing member is arranged on the base
via an abutting member made of a metal.

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 13. A semiconductor device, comprising:
 the semiconductor device substrate as claimed in
claim 1; and
15 a semiconductor element mounted in the opening
forming portion of the semiconductor device substrate.

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 14. A semiconductor device, comprising:
 the semiconductor device substrate as claimed in
claim 2; and
 a semiconductor element mounted in the opening
25 forming portion of the semiconductor device substrate.

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 15. A semiconductor device, comprising:
 the semiconductor device substrate as claimed in
claim 3; and
 a semiconductor element mounted in the opening

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forming portion of the semiconductor device substrate.

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16. A semiconductor device, comprising:

the semiconductor device substrate as claimed in
claim 4; and

a semiconductor element mounted in the opening
10 forming portion of the semiconductor device substrate.

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17. A semiconductor device, comprising:

the semiconductor device substrate as claimed in
claim 5; and

a semiconductor element mounted in the opening
forming portion of the semiconductor device substrate.

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18. A semiconductor device, comprising:

25 the semiconductor device substrate as claimed in
claim 6; and

a semiconductor element mounted in the opening
forming portion of the semiconductor device substrate.